

Yifeng Fu

List of Publications by Year in Descending Order

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The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

64 papers	1,179 citations	19 h-index	32 g-index
80 ext. papers	1,496 ext. citations	6.5 avg, IF	4.26 L-index

#	Paper	IF	Citations
64	Degradation of Carbon Nanotube Array Thermal Interface Materials through Thermal Aging: Effects of Bonding, Array Height, and Catalyst Oxidation. <i>ACS Applied Materials & Interfaces</i> , 2021 , 13, 30992-31000	9.5	4
63	A lightweight and high thermal performance graphene heat pipe. <i>Nano Select</i> , 2021 , 2, 364-372	3.1	5
62	Multiple growth of graphene from a pre-dissolved carbon source. <i>Nanotechnology</i> , 2020 , 31, 345601	3.4	4
61	Effects of high temperature treatment of carbon nanotube arrays on graphite: increased crystallinity, anchoring and inter-tube bonding. <i>Nanotechnology</i> , 2020 , 31, 455708	3.4	5
60	High porosity and light weight graphene foam heat sink and phase change material container for thermal management. <i>Nanotechnology</i> , 2020 , 31, 424003	3.4	7
59	Synthesis of graphene quantum dots and their applications in drug delivery. <i>Journal of Nanobiotechnology</i> , 2020 , 18, 142	9.4	45
58	Graphene related materials for thermal management. <i>2D Materials</i> , 2020 , 7, 012001	5.9	82
57	Scalable three-dimensional Ni3P-based composite networks for flexible asymmetric supercapacitors. <i>Chemical Engineering Journal</i> , 2020 , 380, 122621	14.7	16
56	Experimental Microwave Complex Conductivity Extraction of Vertically Aligned MWCNT Bundles for Microwave Subwavelength Antenna Design. <i>Micromachines</i> , 2019 , 10,	3.3	1
55	A portable micro glucose sensor based on copper-based nanocomposite structure. <i>New Journal of Chemistry</i> , 2019 , 43, 7806-7813	3.6	23
54	Reliability Investigation of a Carbon Nanotube Array Thermal Interface Material. <i>Energies</i> , 2019 , 12, 2080	9.1	6
53	Thermal Characterization of Low-Dimensional Materials by Resistance Thermometers. <i>Materials</i> , 2019 , 12,	3.5	1
52	Covalent Anchoring of Carbon Nanotube-Based Thermal Interface Materials Using Epoxy-Silane Monolayers. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2019 , 9, 427-433	1.7	4
51	Compact and low loss electrochemical capacitors using a graphite / carbon nanotube hybrid material for miniaturized systems. <i>Journal of Power Sources</i> , 2019 , 412, 374-383	8.9	22
50	Understanding noninvasive charge transfer doping of graphene: a comparative study. <i>Journal of Materials Science: Materials in Electronics</i> , 2018 , 29, 5239-5252	2.1	8
49	Egg albumen templated graphene foams for high-performance supercapacitor electrodes and electrochemical sensors. <i>Journal of Materials Chemistry A</i> , 2018 , 6, 18267-18275	13	19
48	Improving Thermal Transport at Carbon Hybrid Interfaces by Covalent Bonds. <i>Advanced Materials Interfaces</i> , 2018 , 5, 1800318	4.6	15

47	Thermal Reliability Study of Polymer Bonded Carbon Nanotube Array Thermal Interface Materials 2018 ,		1
46	Chemical vapor deposition grown graphene on Cu-Pt alloys. <i>Materials Letters</i> , 2017 , 193, 255-258	3.3	12
45	A flexible and stackable 3D interconnect system using growth-engineered carbon nanotube scaffolds. <i>Flexible and Printed Electronics</i> , 2017 , 2, 025003	3.1	5
44	Current status and progress of organic functionalization of CNT based thermal interface materials for electronics cooling applications 2017 ,		2
43	An overview of carbon nanotubes based interconnects for microelectronic packaging 2017 ,		1
42	Synthesis Methods of Two-Dimensional MoS ₂ : A Brief Review. <i>Crystals</i> , 2017 , 7, 198	2.3	82
41	Functionalization mediates heat transport in graphene nanoflakes. <i>Nature Communications</i> , 2016 , 7, 11281	17.4	104
40	Characterization and simulation of liquid phase exfoliated graphene-based films for heat spreading applications. <i>Carbon</i> , 2016 , 106, 195-201	10.4	26
39	Hotspot test structures for evaluating carbon nanotube microfin coolers and graphene-like heat spreaders 2016 ,		1
38	Synthesis and applications of two-dimensional hexagonal boron nitride in electronics manufacturing. <i>Electronic Materials Letters</i> , 2016 , 12, 1-16	2.9	49
37	Mechanical and thermal characterization of a novel nanocomposite thermal interface material for electronic packaging. <i>Microelectronics Reliability</i> , 2016 , 56, 129-135	1.2	12
36	Embedded Fin-Like Metal/CNT Hybrid Structures for Flexible and Transparent Conductors. <i>Small</i> , 2016 , 12, 1521-6	11	12
35	Two-dimensional hexagonal boron nitride as lateral heat spreader in electrically insulating packaging. <i>Journal Physics D: Applied Physics</i> , 2016 , 49, 265501	3	24
34	Controllable and fast synthesis of bilayer graphene by chemical vapor deposition on copper foil using a cold wall reactor. <i>Chemical Engineering Journal</i> , 2016 , 304, 106-114	14.7	12
33	Double-Densified Vertically Aligned Carbon Nanotube Bundles for Application in 3D Integration High Aspect Ratio TSV Interconnects 2016 ,		1
32	Infrared emissivity measurement for vertically aligned multiwall carbon nanotubes (CNTs) based heat spreader applied in high power electronics packaging 2016 ,		4
31	Graphene oxide based coatings on nitinol for biomedical implant applications: effectively promote mammalian cell growth but kill bacteria. <i>RSC Advances</i> , 2016 , 6, 38124-38134	3.7	32
30	Enhanced cold wall CVD reactor growth of horizontally aligned single-walled carbon nanotubes. <i>Electronic Materials Letters</i> , 2016 , 12, 329-337	2.9	4

29	2D heat dissipation materials for microelectronics cooling applications 2016 ,		3
28	Vertically aligned CNT-Cu nano-composite material for stacked through-silicon-via interconnects. <i>Nanotechnology</i> , 2016 , 27, 335705	3-4	28
27	The effects of graphene-based films as heat spreaders for thermal management in electronic packaging 2016 ,		3
26	Combination of positive charges and honeycomb pores to promote MC3T3-E1 cell behaviour. <i>RSC Advances</i> , 2015 , 5, 42276-42286	3-7	7
25	Tape-Assisted Transfer of Carbon Nanotube Bundles for Through-Silicon-Via Applications. <i>Journal of Electronic Materials</i> , 2015 , 44, 2898-2907	1-9	14
24	Vertically Stacked Carbon Nanotube-Based Interconnects for Through Silicon Via Application. <i>IEEE Electron Device Letters</i> , 2015 , 36, 499-501	4-4	31
23	Cooling hot spots by hexagonal boron nitride heat spreaders 2015 ,		4
22	Reliability of graphene-based films used for high power electronics packaging 2015 ,		3
21	Improved Heat Spreading Performance of Functionalized Graphene in Microelectronic Device Application. <i>Advanced Functional Materials</i> , 2015 , 25, 4430-4435	15-6	84
20	Flexible Multifunctionalized Carbon Nanotubes-Based Hybrid Nanowires. <i>Advanced Functional Materials</i> , 2015 , 25, 4135-4143	15-6	17
19	Use of graphene-based films for hot spot cooling 2014 ,		3
18	Thermal characterization of power devices using graphene-based film 2014 ,		6
17	Reliability of carbon nanotube bumps for chip on glass application 2014 ,		2
16	Thermal chemical vapor deposition grown graphene heat spreader for thermal management of hot spots. <i>Carbon</i> , 2013 , 61, 342-348	10-4	72
15	Carbon nanotubes for electronics manufacturing and packaging: from growth to integration. <i>Advances in Manufacturing</i> , 2013 , 1, 13-27	2-7	11
14	Characterization for graphene as heat spreader using thermal imaging method 2013 ,		6
13	Graphene based heat spreader for high power chip cooling using flip-chip technology 2013 ,		6
12	Graphene heat spreader for thermal management of hot spots 2013 ,		4

11	Selective growth of double-walled carbon nanotubes on gold films. <i>Materials Letters</i> , 2012 , 72, 78-80	3-3	18
10	Thick film patterning by lift-off process using double-coated single photoresists. <i>Materials Letters</i> , 2012 , 76, 117-119	3-3	7
9	Templated growth of covalently bonded three-dimensional carbon nanotube networks originated from graphene. <i>Advanced Materials</i> , 2012 , 24, 1576-81	24	34
8	A complete carbon-nanotube-based on-chip cooling solution with very high heat dissipation capacity. <i>Nanotechnology</i> , 2012 , 23, 045304	3-4	50
7	Through-Silicon Vias Filled With Densified and Transferred Carbon Nanotube Forests. <i>IEEE Electron Device Letters</i> , 2012 , 33, 420-422	4-4	49
6	Detecting single molecules inside a carbon nanotube to control molecular sequences using inertia trapping phenomenon. <i>Applied Physics Letters</i> , 2012 , 101, 133105	3-4	2
5	Use of Carbon nanotubes in potential electronics packaging applications 2010 ,		3
4	Application of through silicon via technology for in situ temperature monitoring on thermal interfaces. <i>Journal of Micromechanics and Microengineering</i> , 2010 , 20, 025027	2	8
3	Ultrafast transfer of metal-enhanced carbon nanotubes at low temperature for large-scale electronics assembly. <i>Advanced Materials</i> , 2010 , 22, 5039-42	24	39
2	A study of the heat transfer characteristics of the micro-channel heat sink 2009 ,		1
1	Nanostructured polymer-metal composite for thermal interface material applications 2008 ,		10